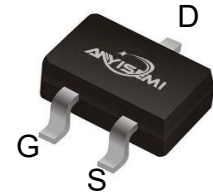


### Description

The Si2308ADT-AY uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



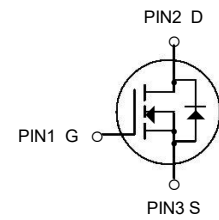
### General Features

- $V_{DS} = 60V, I_D = 4.5A$
- $R_{DS(ON)} < 75m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 90m\Omega @ V_{GS}=4.5V$

### Application

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- PWM applications
- Load switch
- Power management

SOT-23-3L



N-Channel MOSFET

### Package Marking and Ordering Information

| Product ID   | Pack      | Brand | Qty(PCS) |
|--------------|-----------|-------|----------|
| Si2308ADT-AY | SOT-23-3L |       | 3000     |

### Absolute Maximum Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

| Symbol          | Parameter   | Limit      | Unit          |
|-----------------|---|------------|---------------|
| $V_{DS}$        | Drain-Source Voltage  | 60         | V             |
| $V_{GS}$        | Gate-Source Voltage   | $\pm 20$   | V             |
| $I_D$           | Drain Current-Continuous                                    | 4.5        | A             |
| $I_{DM}$        | Drain Current-Pulsed <sup>(Note 1)</sup>                    | 15         | A             |
| $P_D$           | Maximum Power Dissipation                                   | 8          | W             |
| $T_J, T_{STG}$  | Operating Junction and Storage Temperature Range            | -55 To 150 | $^{\circ}C$   |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | 89         | $^{\circ}C/W$ |

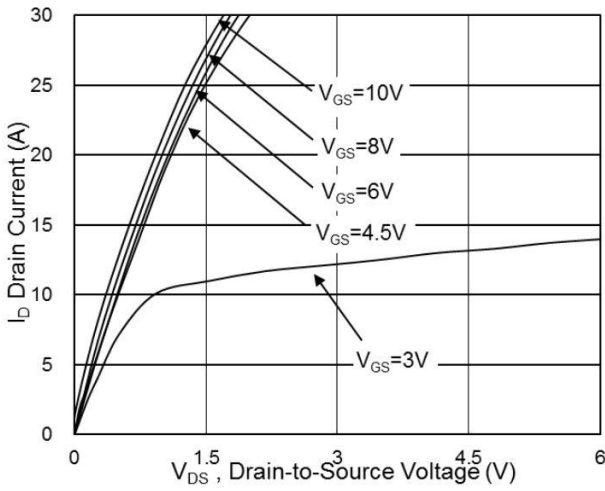
**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

| Symbol              | Parameter                                      | Conditions   | Min. | Typ. | Max. | Unit |
|---------------------|--|--|------|------|------|------|
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage                 | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA   | 60   | ---  | ---  | V    |
| R <sub>DS(ON)</sub> | Static Drain-Source On-Resistance <sup>2</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =5A   | ---  | 70   | 75   | mΩ   |
|                     |  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A  | ---  | 80   | 90   |      |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                         | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA                               | 1.2  | ---  | 2.5  | V    |
| I <sub>DSS</sub>    | Drain-Source Leakage Current                   | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                        | ---  | ---  | 1    | uA   |
|                     |  | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C                        | ---  | ---  | 5    |      |
| I <sub>GSS</sub>    | Gate-Source Leakage Current                    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V   | ---  | ---  | ±100 | nA   |
| g <sub>fs</sub>     | Forward Transconductance                       | V <sub>DS</sub> =5V, I <sub>D</sub> =5A  | ---  | 7    | ---  | S    |
| Q <sub>g</sub>      | Total Gate Charge (10V)                        | V <sub>DS</sub> =12V, V <sub>GS</sub> =10V, I <sub>D</sub> =5A                         | ---  | 5.5  | ---  | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge                             |  | ---  | 1.8  | ---  |      |
| Q <sub>gd</sub>     | Gate-Drain Charge                              |  | ---  | 2.4  | ---  |      |
| T <sub>d(on)</sub>  | Turn-On Delay Time                             | V <sub>DD</sub> =12V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω<br>I <sub>D</sub> =5A | ---  | 6    | ---  | ns   |
| T <sub>r</sub>      | Rise Time                                      |  | ---  | 10   | ---  |      |
| T <sub>d(off)</sub> | Turn-Off Delay Time                            |  | ---  | 15   | ---  |      |
| T <sub>f</sub>      | Fall Time                                      |  | ---  | 7    | ---  |      |
| C <sub>iss</sub>    | Input Capacitance                              | V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz                                      | ---  | 695  | ---  | pF   |
| C <sub>oss</sub>    | Output Capacitance                             |  | ---  | 148  | ---  |      |
| C <sub>rss</sub>    | Reverse Transfer Capacitance                   |  | ---  | 7    | ---  |      |
| I <sub>S</sub>      | Continuous Source Current <sup>1,5</sup>       | V <sub>G</sub> =V <sub>D</sub> =0V, Force Current                                      | ---  | ---  | 17   | A    |
| I <sub>SM</sub>     | Pulsed Source Current <sup>2,5</sup>           |  | ---  | ---  | 50   | A    |
| V <sub>SD</sub>     | Diode Forward Voltage <sup>2</sup>             | V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C                          | ---  | ---  | 1.2  | V    |

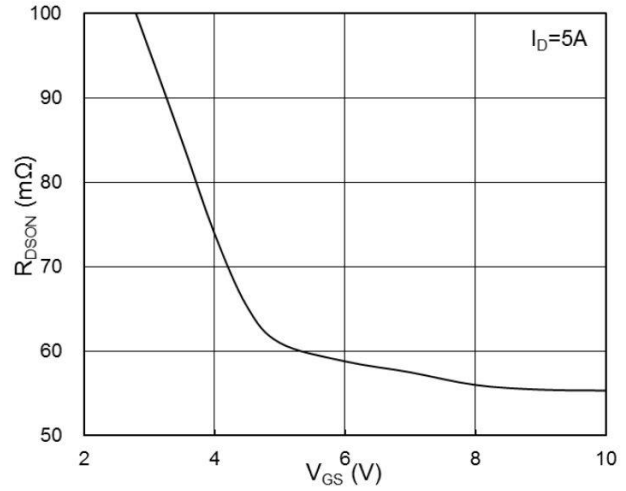
**Note :**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup>FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=15A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

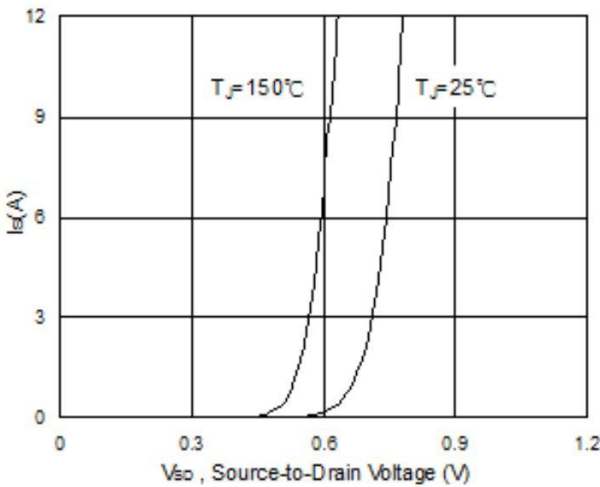
**Typical Characteristics**



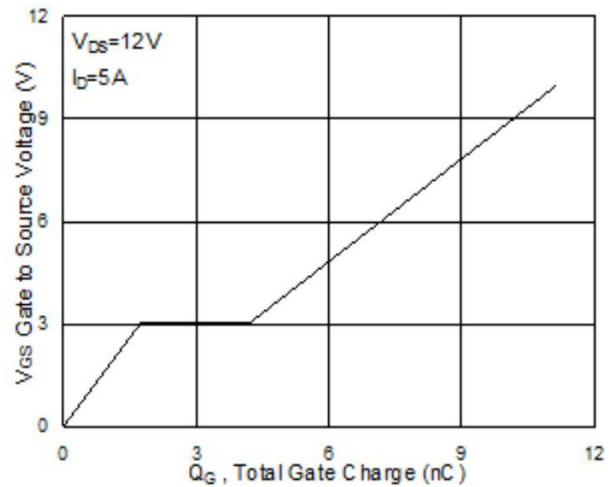
**Fig.1 Typical Output Characteristics**



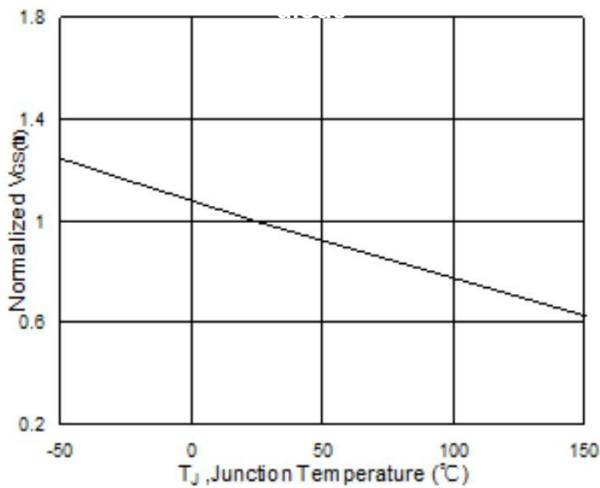
**Fig.2 On-Resistance vs. Gate-Source Voltage**



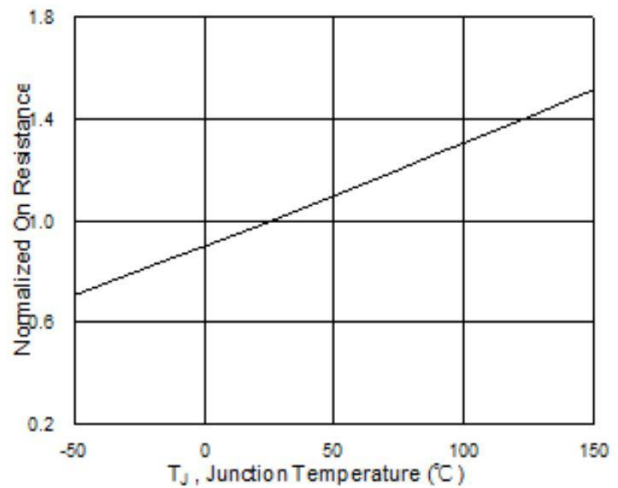
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

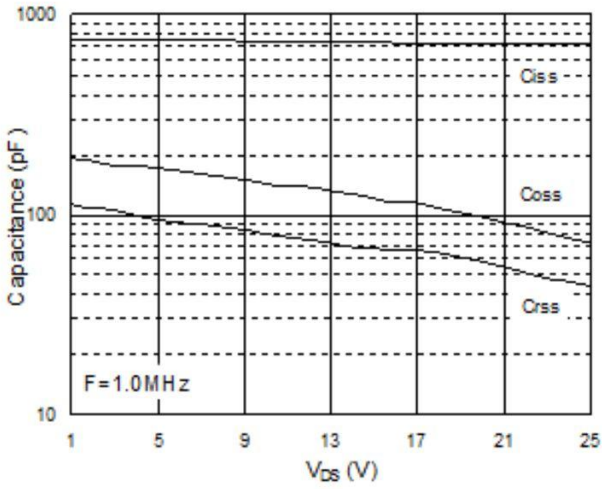


Fig.7 Capacitance

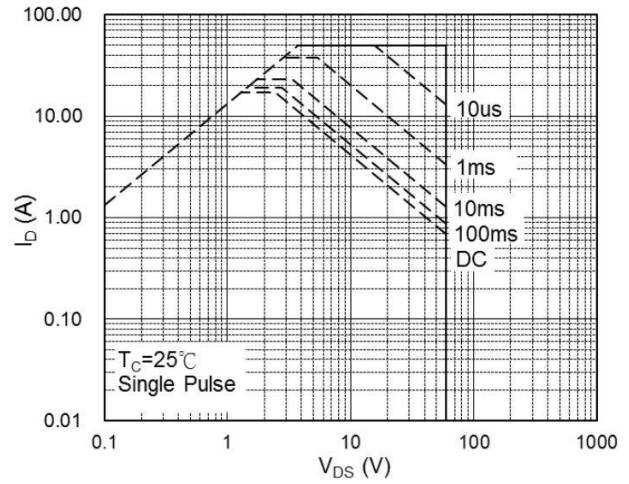


Fig.8 Safe Operating Area

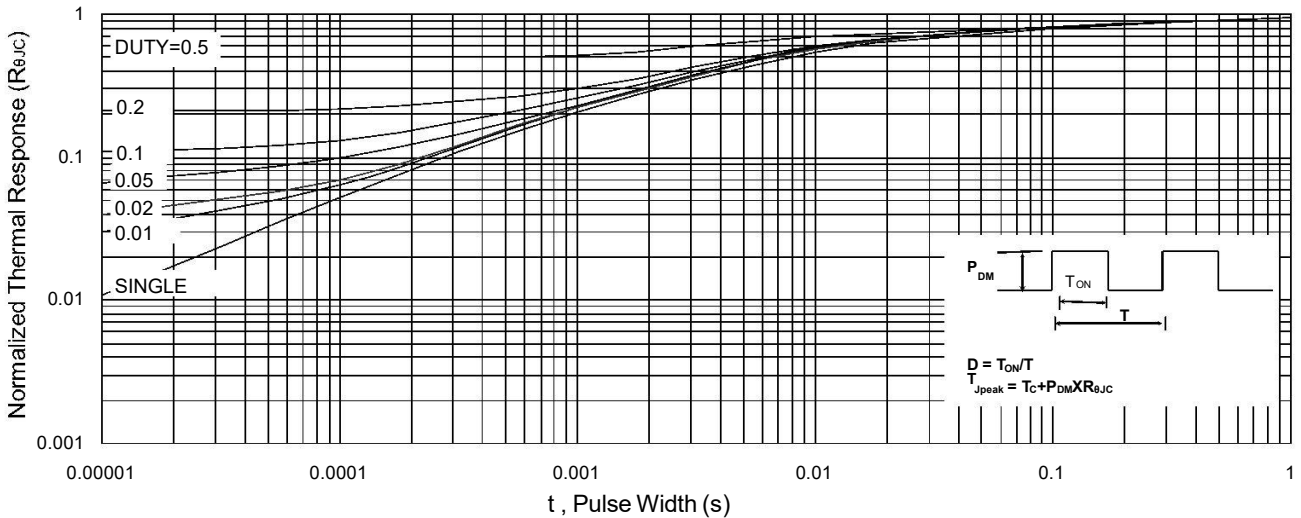


Fig.9 Normalized Maximum Transient Thermal Impedance

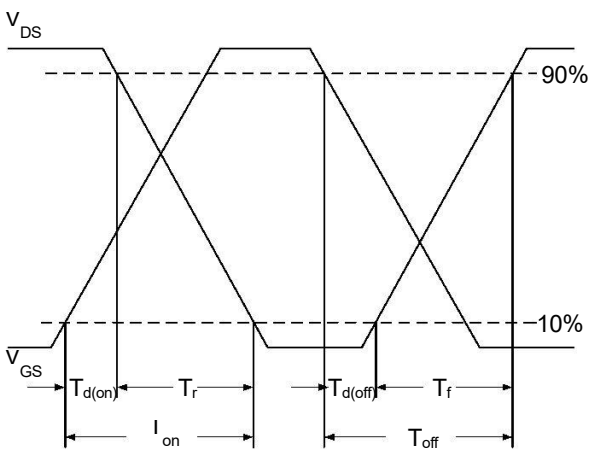


Fig.10 Switching Time Waveform

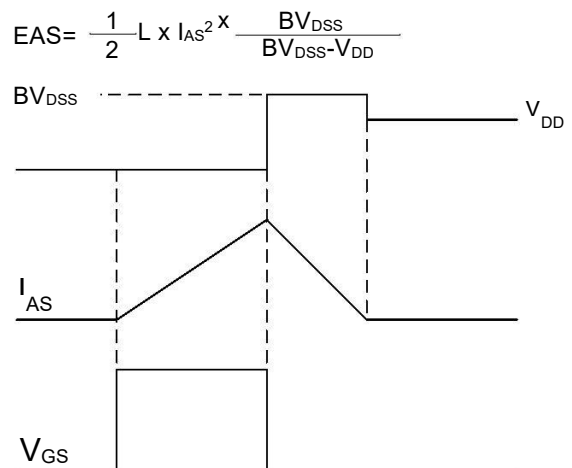
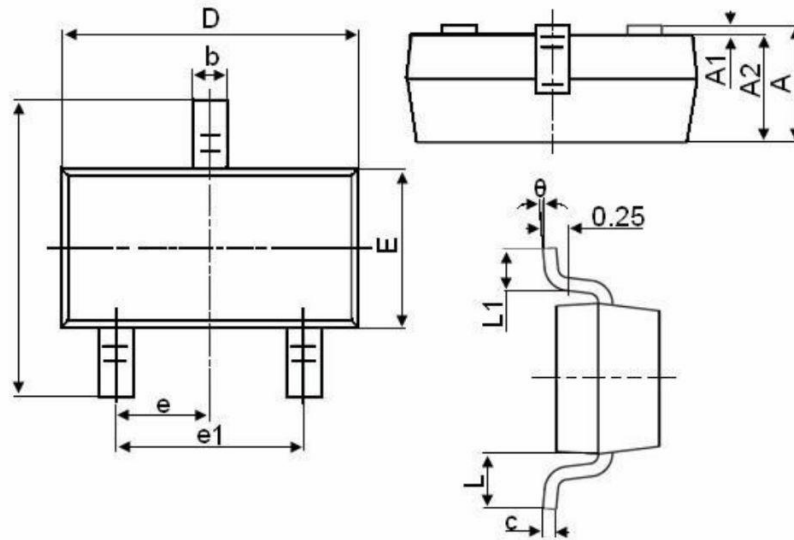


Fig.11 Unclamped Inductive Switching Waveform

**SOT-23-3LPackage Information**


| Symbol | Dimensions in Millimeters |       |
|--------|---------------------------|-------|
|        | MIN.                      | MAX.  |
| A      | 1.050                     | 1.250 |
| A1     | 0.000                     | 0.100 |
| A2     | 1.050                     | 1.150 |
| b      | 0.300                     | 0.500 |
| c      | 0.100                     | 0.200 |
| D      | 2.800                     | 3.000 |
| E      | 1.500                     | 1.700 |
| E1     | 2.650                     | 2.950 |
| e      | 0.950TYP                  |       |
| e1     | 1.800                     | 2.000 |
| L      | 0.550REF                  |       |
| L1     | 0.300                     | 0.600 |
| θ      | 0°                        | 8°    |

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